

Product Change Notice (PCN)

Subject: Alternate Bump Location and Assembly Location on Select Device from FCCSP-240

Publication Date: 11/22/2024

Effective Date: 2/21/2025

Revision Description:

Initial Release

Description of Change:

Renesas is adding JCAP, China as an alternate Bump location and JSCC, China as alternate Assembly location in expanding the supply chain on select device from FCCSP-240. The alternate locations are the current qualified location for Renesas. The material sets of the current and the alternate assembly location are as shown in the below table. There will be changes in the material sets, equipment models, inspection items and sampling at the alternate locations.

There will be no change in the moisture sensitive level.

Material Sets	Existing Bump & Assembly ASEC, Taiwan	Alternate Bump & Assembly JCAP, China & JSCC, China
Die Bump	Copper Pillar 37Cu/3Ni/25SnAg	Copper Pillar 37Cu/3Ni/25SnAg
Mold Compound	EME-G311AC	EME-G311A Type C
Substrate/Supplier	GHPL830NS+SR1 (UMTC Taiwan)	GHPL830NS+SR1 (Simmtech Korea)
Solder Balls	0.305mm LF35	0.305mm LF35

Affected Product List: RRG50040-A00, RRG50041-A00.

Reason for Change:

The change is to create dual source to secure business continuity.

Impact on Fit, Form, Function, Quality & Reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the products.

Product Identification:

Assembly lot# prefix denote Assembly Location

Prefix	Assembly Location
RC	ASEC Taiwan
JS	JSCC, China

Qualification Status: Completed. Refer Appendix A
Sample Availability Date: Eight weeks from customer request
Device Material Declaration: Available upon request

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact idt-pcn@lm.renesas.com

Appendix A - Qualification Results
Affected Package: FCCSP-240

Qual Vehicle: FCCSP-240

Assembly Material: As shown on page 1

Qual Plan & Results: Tests are in accordance with JEDEC47 recommended tests.

Test Descriptions	Test Method	Test Results (Rej/SS)		
		Lot 1	Lot 2	Lot 3
* Temperature Cycling (-55 °C to 125 °C, 700 cycles)	JESD22-A104	0/25	0/25	0/25
* HAST - biased (130 °C/85% RH, 96 Hrs)	JESD22-A110	0/25	0/25	0/25
* HAST - unbiased (130 °C/85% RH, 96 Hrs)	JESD22-A118	0/25	0/25	0/25
High Temperature Storage Bake (150 °C, 1000 Hrs)	JESD22-A103	0/25	0/25	0/25
Physical Dimensions	JESD22-B100	0/30	0/30	0/30
Solderability Test	MIL-STD-883 (Method 2003)	0/5	0/5	0/5
Solder Ball Shear Test (1000 Hrs)	JESD22-B117	0/5	0/5	0/5
Moisture Sensitivity Level, MSL	J-STD-20 / MSL 3, 260 °C	0/25	0/25	0/25

*Tests were subjected to Preconditioning per JESD22-A113 prior to stress test